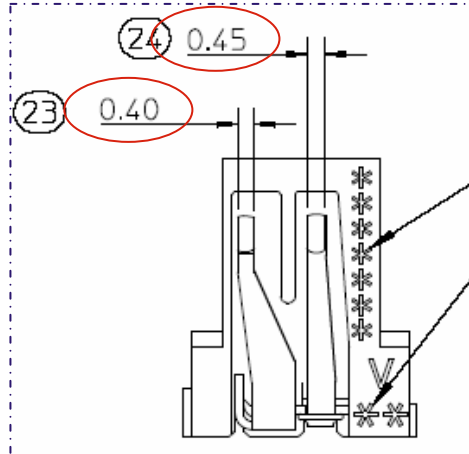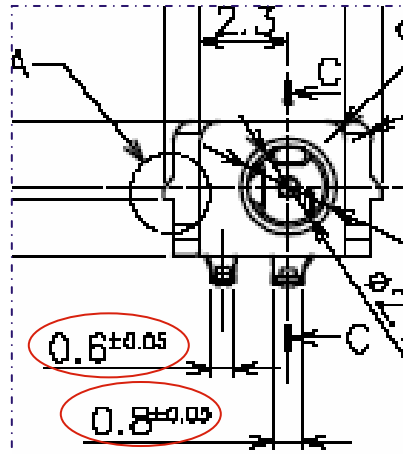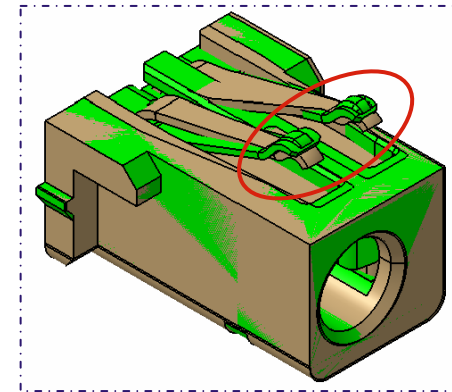# Difference between Springs

The width of spring of Foxconn's is more wide than Molex's.
The height of spring of Foxconn's is higher than Molex's in 3D.
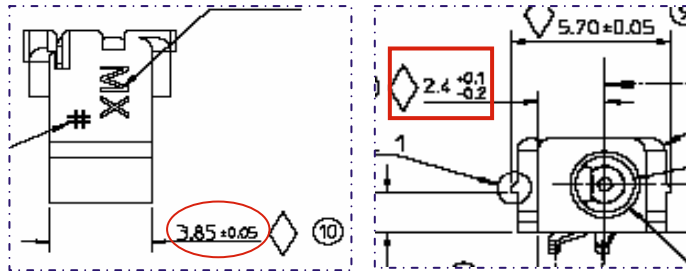So after assembled with PCB, Foxconn's contact better than Molex's.

Molex

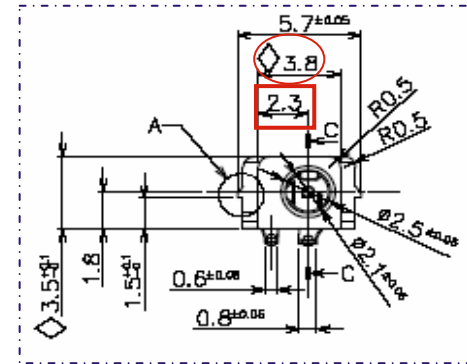

Foxconn

Comparation
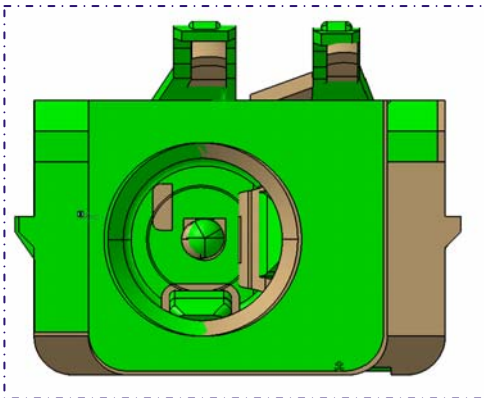**(Green is Foxconn's, Brown is Molex's)**
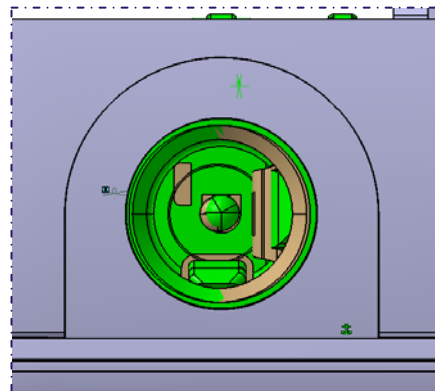
The Hole Location
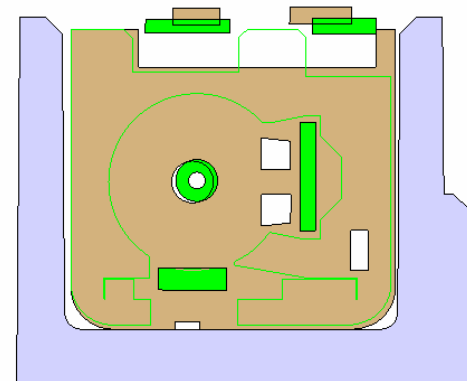

Molex

Foxconn

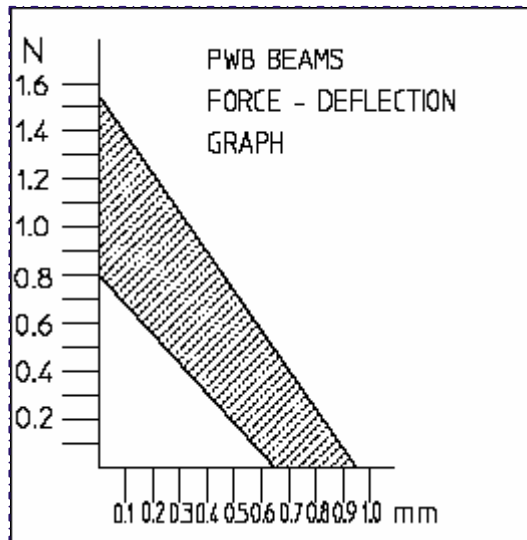**The hole center are not align if assembled to B_Cover_Blank. However the Molex's is**

(Green is Foxconn's, Brown is Molex's)

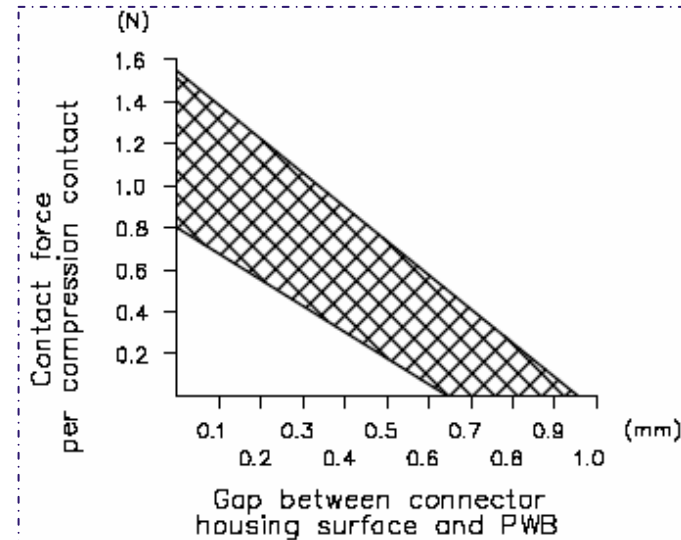
Section View after assembled to B_Cover_Blank

Build Your Dreams

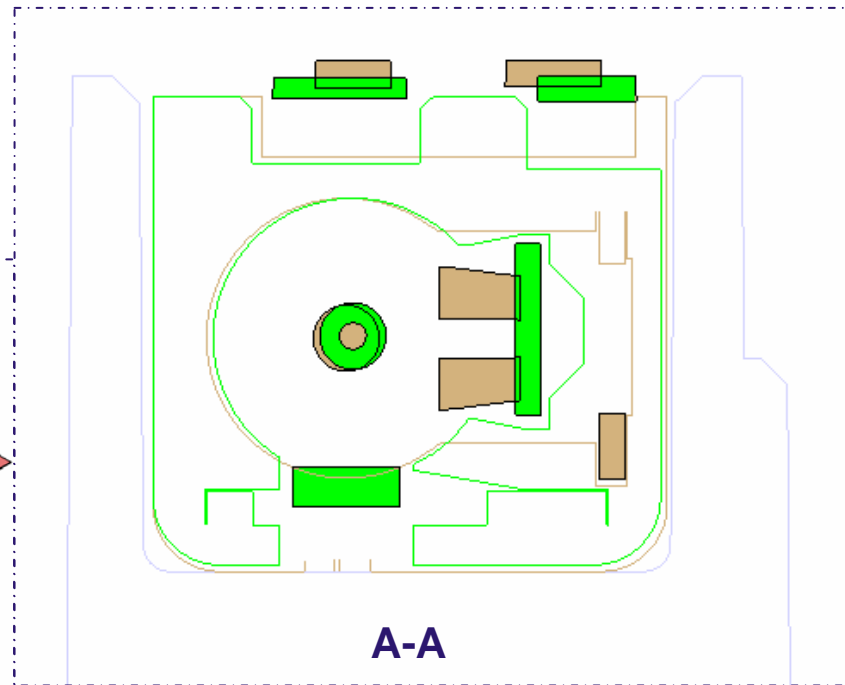**Foxconn's PWB Beams Force – Deflection Graph is the same as Molex's.**
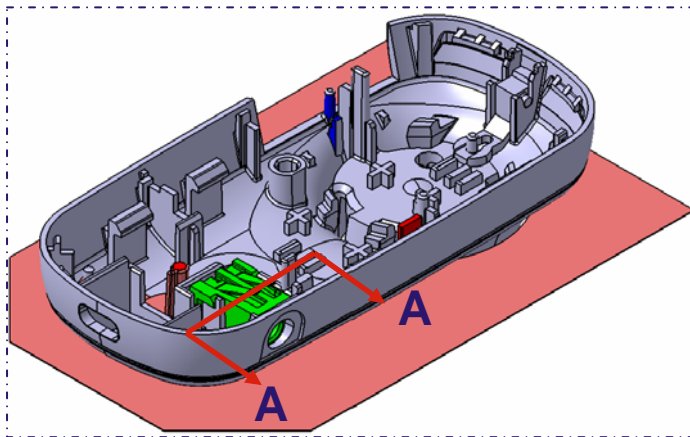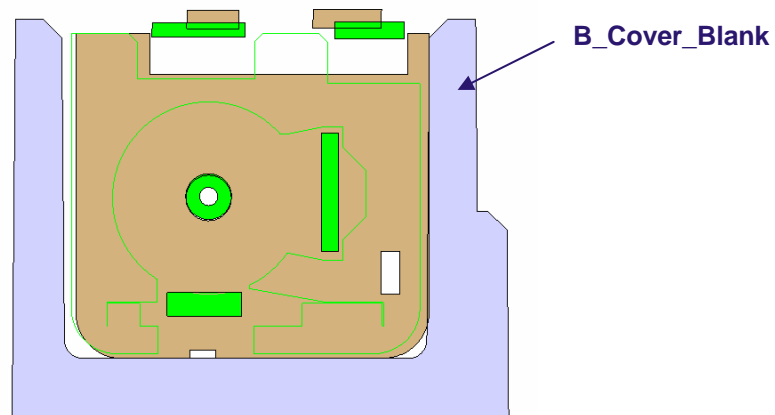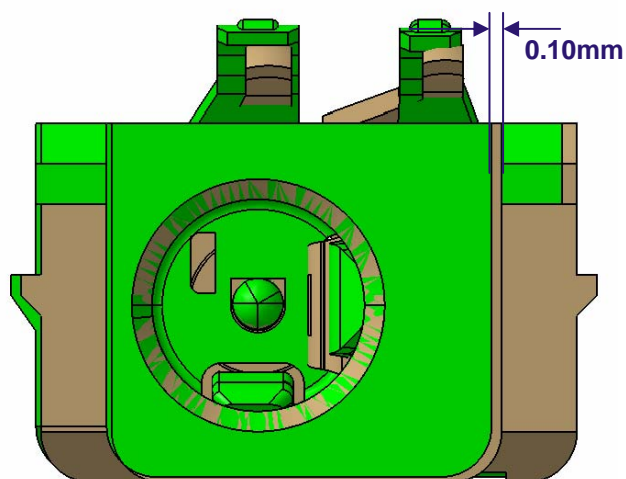

Molex

Foxconn

3D design of Pehi is based on Foxconn DC_Jack.
So the dimension of B_Cover_Blank is more suitable to Foxconn DC_Jack.

A-A

(Green is Foxconn's, Brown is Molex's)

When align the center with B_Cover_Blank Hole, Molex's is at Foxconn's right 0.10mm.
And Molex's reference with B_Cover_Blank as fig. show bellow.

0.10mm

B_Cover_Blank

Section View after assembled to B_Cover_Blank

(Green is Foxconn's, Brown is Molex's)